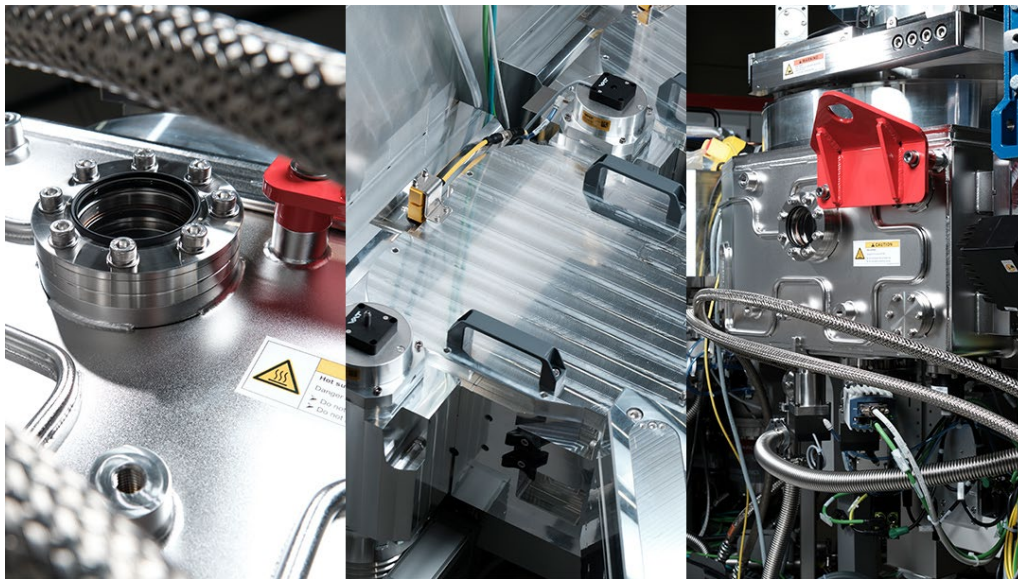


Evatec delivers first CLUSTERLINE® 310 for Advanced Packaging on small panel formats

Evatec has delivered its first dedicated CLUSTERLINE® 310 for panel level packaging on 310×310mm panel formats to a leading global IDM. The tool will be used to support their next generation chip manufacturing and integrates degas, etch and PVD technologies for processing of glass and highly outgassing organics. This delivery marks the beginning of a robust pipeline of global customer orders, with further deliveries scheduled over the coming months.

Evatec Business Field Manager Admir Asanoski commented: “As the market leader in delivering packaging solutions for larger panels up to 650mm around the globe over the last 8 years, our team has gained a deep understanding of the challenges of panel processing and the cost benefits of manufacturing on larger package sizes in areas like HPC and AI. The emerging requests for 310mm solutions from our customers presented the perfect opportunity for our team to leverage existing engineering and process know-how and fast track development of a new dedicated tool for 310mm. From Fan-Out Panel-Level Packaging (FOPLP) to CoPoS architectures, our new CLUSTERLINE® 310 solution delivers the required process uniformities and process yield essential for a successful scale up with lower initial tool investment costs and built in platform flexibility that supports our customers’ technology roadmaps. We are excited to be at the forefront of providing production solutions in this rapidly growing market segment.”



About Evatec

As a global leader in thin film technology Evatec designs and manufactures production systems for industry across applications in Advanced Packaging, Semiconductor, Optoelectronics and Photonics, whilst its customized engineering solutions support the equipment needed at the world's leading R&D institutions. For more information visit <https://evatecnet.com>. For press enquiries please contact Allan Jaunzens. allan.jaunzens@evatecnet.com